

LM3712

Microprocessor Supervisory Circuits with Separate Watchdog Timer Output, Power Fail Input and Manual Reset

General Description

The LM3712 series of microprocessor supervisory circuits provide the maximum flexibility for monitoring power supplies and battery controlled functions in systems without backup batteries. The LM3712 series are available in a 9-bump micro SMD package.

Built-in features include the following:

Reset: Reset is asserted during power-up, power-down, and brownout conditions. $\overline{\text{RESET}}$ is guaranteed down to V_{CC} of 1.0V.

Manual Reset Input: An input that asserts reset when pulled low

Power-Fail Input: A 1.225V threshold detector for power fail warning, or to monitor a power supply other than $V_{\rm CC}$.

Watchdog Timer: The WDI (Watchdog Input) monitors one of the μP 's output lines for activity. If no output transition occurs during the watchdog timeout period, the watchdog output (\overline{WDO}) pulls low.

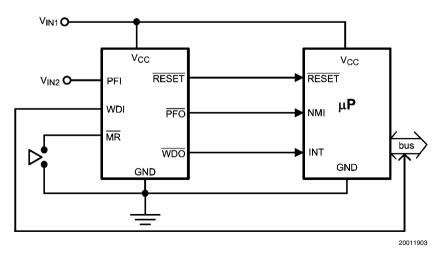
Features

- Standard Reset Threshold voltage: 3.08V
- Custom Reset Threshold voltages: For other voltages between 2.2V and 5.0V in 10mV increments, contact National Semiconductor Corp.
- No external components required
- Manual-Reset input
- RESET output
- Precision supply voltage monitor
- Factory programmable Reset and Watchdog Timeout Delays
- Separate Watchdog output
- Separate Power Fail comparator
- Available in micro SMD package for minimum footprint
- ±0.5% Reset threshold accuracy at room temperature
- ±2% Reset threshold accuracy over temperature extremes
- Reset assertion down to 1V V_{CC}
- 28 µA V_{CC} supply current

Applications

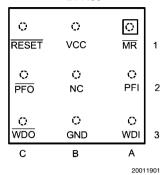
- Embedded Controllers and Processors
- Intelligent Instruments
- Automotive Systems
- Critical µP Power Monitoring

Typical Application



Connection Diagram

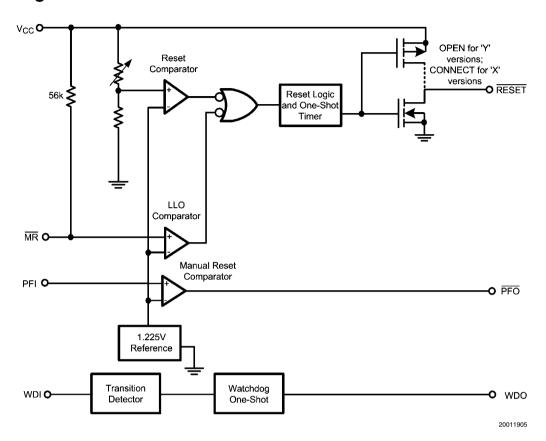
Top View (looking from the coating side) micro SMD 9 Bump Package BPA09



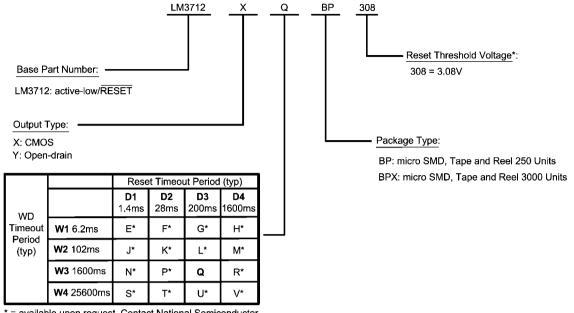
Pin Descriptions

Bump No.	Name	Function
A1	MR	Manual-Reset input. When $\overline{\text{MR}}$ is less than V_{MRT} (Manual Reset Threshold) $\overline{\text{RESET}}$ is engaged.
B1	V _{CC}	Power Supply input.
C1	RESET	Reset Logic Output. Pulses low for t_{RP} (Reset Timeout Period) when triggered, and stays low whenever V_{CC} is below the reset threshold or when \overline{MR} is below V_{MRT} . It remains low for t_{RP} after either V_{CC} rises above the reset threshold, or after \overline{MR} input rises above V_{MRT} .
C2	PFO	Power-Fail Logic Output. When PFI is below V _{PFT} PFO goes low; otherwise, PFO remains high.
C3	WDO	Watchdog Output. If no digital activity is detected on WDI (Watchdog Input) for a period exceeding t_{WD} , this output pulls low.
B3	GND	Ground reference for all signals.
A3	WDI	Watchdog Input Transition Monitor: If no transition activity occurs for a period exceeding t _{WD} (Watchdog Timeout Period), reset is engaged.
A2	PFI	Power-Fail Comparator Input. When PFI is less than V _{PFT} (Power-Fail Reset Threshold), the PFO goes low; otherwise, PFO remains high.
B2	NC	No Connect. Test input used at factory only. Leave floating.

Block Diagram



Ordering Information



^{* =} available upon request. Contact National Semiconductor

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*For other voltages between 2.2V and 5.0V, please contact National Semiconductor sales office.

Part Number	Output	Reset Timeout Period	Watchdog Timeout Period	Package Marking
LM3712XQBP-308	totem-pole	200ms	1600ms	%%IC
LM3712XQBPX-308	totem-pole	200ms	1600ms	%%IC
LM3712XQTP-308	totem-pole	200ms	1600ms	%%IC
LM3712XQTPX-308	totem-pole	200ms	1600ms	%%IC

^{%%} is the datecode and will vary with time.

Table Of Functions

Part Number	Active Low Reset	High	Output (X = totem-pole) (Y = open-drain)	Reset Timeout Period	Watchdog Timeout Period	Manual Reset	Power Fail Comparator
LM3712	х		X, Y*	Customized	Customized	Х	х

^{* =} available upon request. Contact National

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

ESD Ratings (Note 2) Human Body Model Machine Model Power Dissipation

1.5kV 150V (Note 3)

Supply Voltage (V_{CC}) All Other Inputs

-0.3V to 6.0V -0.3V to $V_{CC} + 0.3$ V

Operating Ratings (Note 1)

Temperature Range

 $-40^{\circ}\text{C} \le \text{T}_{\text{J}} \le 85^{\circ}\text{C}$

Electrical Characteristics

Limits in the standard typeface are for T_J = 25°C and limits in **boldface type** apply over full operating range. Unless otherwise specified: V_{CC} = +2.2V to 5.5V.

Symbol	Parameter	Conditions	Min	Тур	Max	Uni
POWER SU	JPPLY					
V _{CC}	Operating Voltage Range: V _{CC}		1.0		5.5	V
I _{cc}	V _{CC} Supply Current	All inputs = V _{CC} ; all outputs floating		28	50	μA
RESET TH	RESHOLD					
V _{RST}	Reset Threshold	V _{CC} falling	-0.5		+0.5	
			-2	V _{RST}	+2	%
		V _{CC} falling: T _A = 0°C to 70°C	-1.5		+1.5	
V _{RSTH}	Reset Threshold Hysteresis			0.0032•V _{RST}		m
t _{RP}	Reset Timeout	Reset Timeout Period = E, J, N, S	1	1.4	2	
	Period	Reset Timeout Period = F, K, P, T	20	28	40	
		Reset Timeout Period = G, L, Q, U	140	200	280	m
		Reset Timeout Period = H, M, R, V	1120	1600	2240	
t_{RD}	V _{CC} to Reset Delay	V _{CC} falling at 1mV/μs		20		μ
ESET	•	•	•	•		
V _{OL}	RESET	V _{CC} > 1.0V, I _{SINK} = 50μA			0.3	
		V _{CC} > 1.2V, I _{SINK} = 100μA			0.3	
		$V_{CC} > 2.25V$, $I_{SINK} = 900\mu A$			0.3	1
		$V_{CC} > 2.7V$, $I_{SINK} = 1.2mA$			0.3	1
		$V_{CC} > 4.5V, I_{SINK} = 3.2mA$			0.4	۱ ۱
V _{OH}	RESET	$V_{CC} > 2.25V$, $I_{SOURCE} = 300\mu A$	0.8 V _{CC}			1
OH		$V_{CC} > 2.7V$, $I_{SOURCE} = 500\mu A$	0.8 V _{CC}			1
		$V_{CC} > 4.5V$, $I_{SOURCE} = 800\mu A$	V _{CC} - 1.5V			┨
VDI	1	VCC > 4.5 V, ISOURCE = 000μΛ	VCC - 1.5V			
	Watahdag Input	1	1	1	. 4	Τ
WDI	Watchdog Input Current		-1		+1	μ,
WDI _T	Watchdog Input Threshold		0.2•V _{CC}	1.225	0.8•V _{CC}	\
t_{WD}	Watchdog Timeout	Watchdog Timeout Period = E, F, G, H	4.3	6.2	9.3	
	Period	Watchdog Timeout Period = J, K, L, M	71	102	153	m
		Watchdog Timeout Period = N, P, Q, R	1120	1600	2400	"
		Watchdog Timeout Period = S, T, U, V	17900	25600	38400	
FI/MR		1	Г	1		_
V_{PFT}	PFI Input Threshold		1.200	1.225	1.250	١ ٧
V_{MRT}	MR Input Threshold	MR, Low			0.8	, ا
		MR, High	2.0			<u> </u>
V _{PFTH} / V _{MRTH}	PFI/MR Threshold Hysteresis	PFI/ \overline{MR} falling: $V_{CC} = V_{RST MAX}$ to 5.5V		0.0032•V _{RST}		m
I _{PFI}	Input Current (PFI only)		-75		75	n,

Symbol	Parameter	Conditions	Min	Тур	Max	Units
R _{MR}	MR Pull-up		35	56	75	kΩ
	Resistance					
t _{MD}	MR to Reset Delay			12		μS
t _{MR}	MR Pulse Width		25			μS
PFO, WDO	Ī					
V _{OL}	PFO, WDO Output	$V_{CC} > 2.25V$, $I_{SINK} = 900\mu A$			0.3	
	Voltage	$V_{CC} > 2.7V, I_{SINK} = 1.2mA$			0.3	
		$V_{CC} > 4.5V, I_{SINK} = 3.2mA$			0.4] ,,
V _{OH}		$V_{CC} > 2.25V, I_{SOURCE} = 300\mu A$	0.8 V _{CC}			V
		$V_{CC} > 2.7V$, $I_{SOURCE} = 500\mu A$	0.8 V _{CC}			
		$V_{CC} > 4.5V$, $I_{SOURCE} = 800 \mu A$	V _{CC} - 1.5V			
LLO OUTP	PUT		•			
V _{LLOT}	LLO Output		1.01•V _{RST}	1.02•V _{RST}	1.03•V _{RST}	V
	Threshold					
	$(V_{\overline{LLO}} - V_{RST}, V_{CC})$					
	falling)					
V _{LLOTH}	Low-Line			0.0032•V _{RST}		mV
220	Comparator					
	Hysteresis					
t _{CD}	Low-Line	V _{CC} falling at 1mV/μs		20		μs
	Comparator Delay					

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed conditions.

Note 2: The Human Body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin. The machine model is a 200pF capacitor discharged directly into each pin.

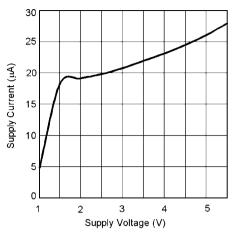
Note 3: The maximum allowable power dissipation is a function of the maximum junction temperature, $T_J(MAX)$, the junction-to-ambient thermal resistance, θ_{JL} , and the ambient temperature, T_A . The maximum allowable power dissipation at any ambient temperature is calculated using:

$$P(MAX) = \frac{T_{J}(MAX) - T_{A}}{\theta_{J-A}}$$

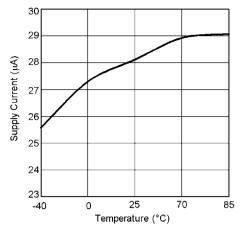
Where the value of $\theta_{\text{J-A}}$ for the micro SMD package is 220°C/W.

Typical Performance Characteristics

Supply Current vs Supply Voltage

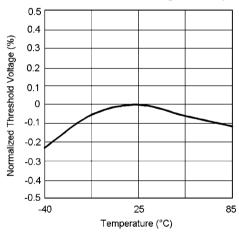


3.3V Supply Current vs Temperature



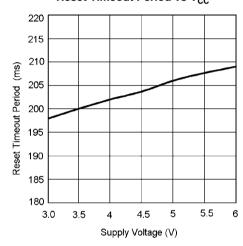
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Normalized Reset Threshold Voltage vs Temperature

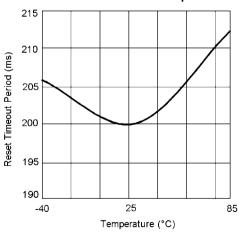


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Reset Timeout Period vs V_{CC}

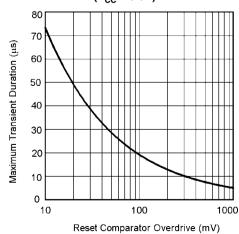


Reset Timeout Period vs Temperature



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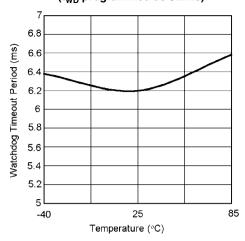
Max. Transient Duration vs Reset Comparator Overdrive $(V_{CC} = 3.3V)$



 $V_{\rm RST}$ - $V_{\rm CC}$

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Watchdog Timeout Period vs Temperature (two programmed as 6.2ms)



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Circuit Information

RESET OUTPUT

The Reset input of a μP initializes the device into a known state. The LM3712 microprocessor supervisory circuits assert a forced reset output to prevent code execution errors during power-up, power-down, and brownout conditions.

 $\overline{\text{RESET}} \text{ is guaranteed valid for V}_{\text{CC}} > 1\text{V. Once V}_{\text{CC}} \text{ exceeds}$ the reset threshold, an internal timer maintains the output for the reset timeout period. After this interval, reset goes high. The LM3712 offers an active-low $\overline{\text{RESET}}$.

Any time V_{CC} drops below the reset threshold (such as during a brownout), the reset activates. When V_{CC} again rises above the reset threshold, the internal timer starts. Reset holds until V_{CC} exceeds the reset threshold for longer than the reset timeout period. After this time, reset releases.

The Manual Reset input (\overline{MR}) will initiate a forced reset also. See the *Manual Reset Input* section.

RESET THRESHOLD

The LM3712 family is available with a reset voltage of 3.08V. Other reset thresholds in the 2.20V to 5.0V range, in steps of 10 mV, are available; contact National Semiconductor for details.

MANUAL RESET INPUT (MR)

Many μP -based products require a manual reset capability, allowing the operator to initiate a reset. The \overline{MR} input is fully debounced and provides an internal 56 k Ω pull-up. When the \overline{MR} input is pulled below V_{MRT} (1.225V) for more than 25 μs , reset is asserted after a typical delay of 12 μs . Reset remains active as long as \overline{MR} is held low, and releases after the reset timeout period expires after \overline{MR} rises above V_{MRT} . Use \overline{MR} with digital logic to assert or to daisy chain supervisory circuits. It may be used as another low-line comparator by adding a buffer.

POWER-FAIL COMPARATOR (PFI/PFO)

The PFI is compared to a 1.225V internal reference, V_{PFT} . If PFI is less than V_{PFT} , the Power Fail Output \overline{PFO} drops low. The power-fail comparator signals a falling power supply, and is driven typically by an external voltage divider that senses either the unregulated supply or another system supply voltage. The voltage divider generally is chosen so the voltage at PFI drops below V_{PFT} several milliseconds before the main

supply voltage drops below the reset threshold, providing advanced warning of a brownout.

The voltage threshold is set by ${\rm R}_{\rm 1}$ and ${\rm R}_{\rm 2}$ and is calculated as follows:

$$V_{PFT} = \left(\frac{R1 + R2}{R2}\right) \times 1.225V$$

Note this comparator is completely separate from the rest of the circuitry, and may be employed for other functions as needed.

WATCHDOG TIMER INPUT (WDI)

The watchdog timer input monitors one of the microprocessor's output lines for activity. Each time a transition occurs on this monitored line, the watchdog counter is reset. However, if no transition occurs and the timeout period is reached, the LM3712 assumes that the microprocessor has locked up and the watchdog output $\overline{\text{WDO}}$, is activated.

WDI is a high impedance input. $\overline{\text{WDO}}$ is an active-low totem pole output.

SPECIAL PRECAUTIONS FOR THE micro SMD PACKAGE

As with most integrated circuits, the LM3712 is sensitive to exposure from visible and infrared (IR) light radiation. Unlike a plastic encapsulated IC, the micro SMD package has very limited shielding from light, and some sensitivity to light reflected from the surface of the PC board or long wavelength IR entering the die from the side may be experienced. This light could have an unpredictable affect on the electrical performance of the IC. Care should be taken to shield the device from direct exposure to bright visible or IR light during operation.

micro SMD MOUNTING

The micro SMD package requires specific mounting techniques which are detailed in National Semiconductor Application Note AN-1112. Referring to the section *Surface Mount Technology (SMT) Assembly Considerations*, it should be noted that the pad style which must be used with the 9-pin package is the NSMD (non-solder mask defined) type.

For best results during assembly, alignment ordinals on the PC board may be used to facilitate placement of the micro SMD device.

Timing Diagrams

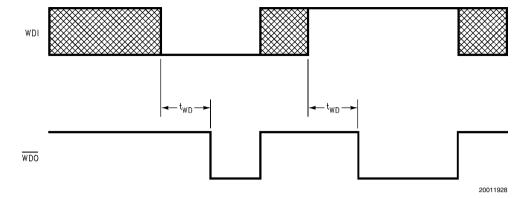


FIGURE 1. LM3712 Reset Time with $\overline{\text{MR}}$

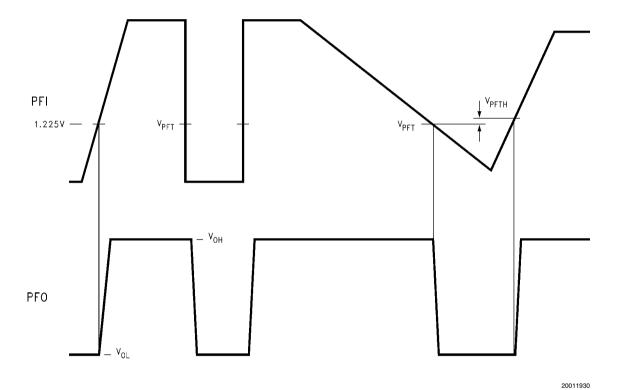


FIGURE 2. PFI Comparator Timing Diagram

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Typical Application Circuits

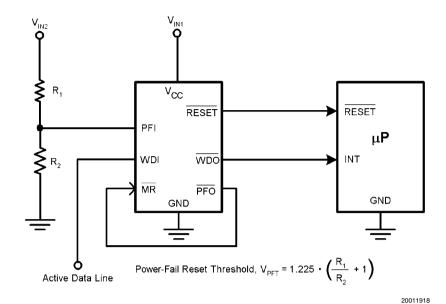


FIGURE 3. Monitoring Two Critical Supplies Plus Dataline

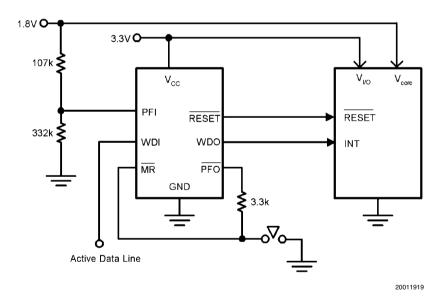
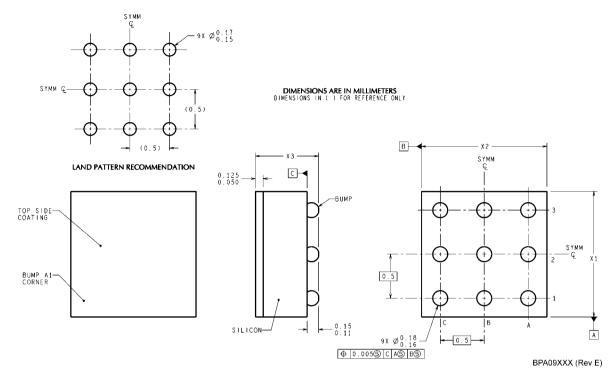


FIGURE 4. Monitoring Two Supplies plus Manual Reset And Dataline

Physical Dimensions inches (millimeters) unless otherwise noted



NOTES: UNLESS OTHERWISE SPECIFIED

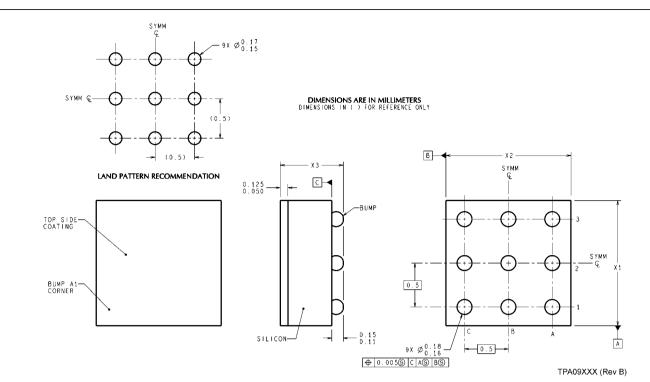
- 1. EPOXY COATING
- 2. 63Sn/37Pb EUTECTIC BUMP
- 3. RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
- 4. PIN 1 IS ESTABLISHED BY LOWER LEFT CORNER WITH RESPECT TO TEXT ORIENTATION. REMAINING PINS ARE NUMBERED COUNTER CLOCK-
- 5. XXX IN DRAWING NUMBER REPRESENTS PACKAGE SIZE VARIATION WHERE X1 IS PACKAGE WIDTH, X2 IS PACKAGE LENGTH AND X3 IS PACK-AGE HEIGHT.

6.NO JEDEC REGISTRATION AS OF AUG.1999.

9 bump micro SMD Package NS Package Number BPA09FFB The dimensions of X1, X2 and X3 are given below

X1 = 1.412mm

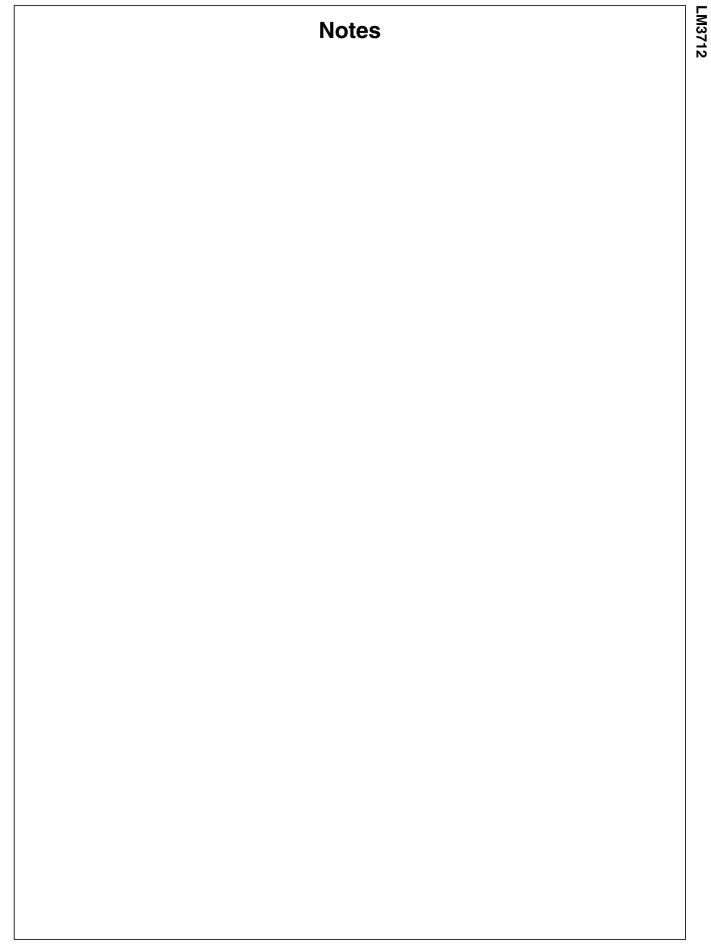
X2 = 1.412mm X3 = 0.850mm



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. EPOXY COATING
- 2. 63Sn/37Pb EUTECTIC BUMP
- 3. RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
- 4. PIN 1 IS ESTABLISHED BY LOWER LEFT CORNER WITH RESPECT TO TEXT ORIENTATION. REMAINING PINS ARE NUMBERED COUNTER CLOCK-WISE
- 5. XXX IN DRAWING NUMBER REPRESENTS PACKAGE SIZE VARIATION WHERE X1 IS PACKAGE WIDTH, X2 IS PACKAGE LENGTH AND X3 IS PACKAGE HEIGHT.
- 6.NO JEDEC REGISTRATION AS OF AUG.1999.

9 bump micro SMD Package
NS Package Number TPA09GGA
The dimensions of X1, X2 and X3 are given below
X1 = 1.412mm
X2 = 1.412mm
X3 = 0.50mm



Notes

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Interface	www.national.com/interface	Quality and Reliability	www.national.com/quality	
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